

# **SPECIFICATION**

Version No.: V2.1

常州	昊 翔	电	子	有限	公 司			
Changzhou HaoXiang Electronic Co., LTD								
客户名	3 称							
CUSTOME	R NAMER :							
产品名	3 称							
COMMOD	ITY :	SMD	MAGN	ETIC BUZ	ZZER			
产品型	产品型号							
MODEL N	MODEL NO : TDA-M90040-0327							
客户米	客户料号							
PART NO	:							
审核	秦皓		主	办	潘莲 Nov.05,2019			
	客户	承	认认	栏				
承	认			拒	收			

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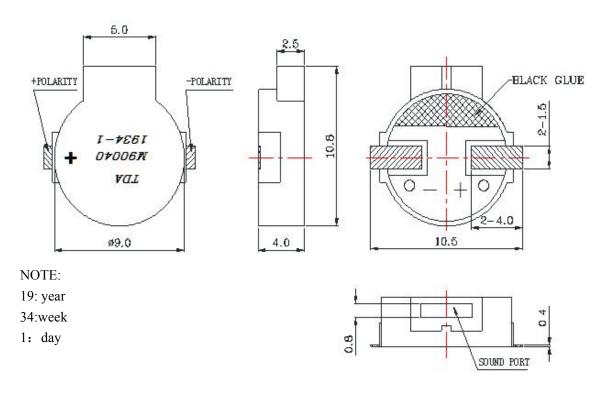
# A. SCOPE

This specification applies magnetic buzzer, **TDA-M90040-0327** 

## **B. SPECIFICATION**

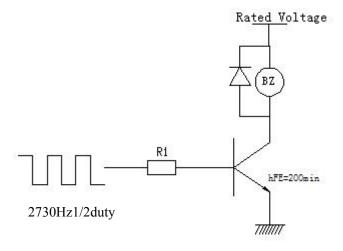
No.	Item	Unit	Specification	Condition
1	Oscillation Frequency	Hz	2730	Square Wave
2	Operating Voltage	Vo-p	2.5~4.5	
3	Rated Voltage	Vo-p	3.6	
4	Current Consumption	mA	MAX. 100	at 3.6Vo-p, 2730Hz, 1/2 duty
5	Sound Pressure Level	dB	MIN. 85	at 10cm at 3.6Vo-p, 2730Hz,1/2 duty
6	Coil Resistance	Ω	16±3	
7	Operating Temperature	$^{\circ}\!\mathbb{C}$	-30-+70	
8	Storage Temperature	$^{\circ}\!\mathbb{C}$	-40-+80	
9	Dimension	mm	Ф9.0х Н4.0	See appearance drawing
10	Weight (MAX)	gram	0.8	
11	Housing Material		PPS( Black )	
12	Leading Pin		Tin Plated Au	See appearance drawing
13	Environmental Protection Regulation		RoHS	

## C. APPEARANCE DRAWING

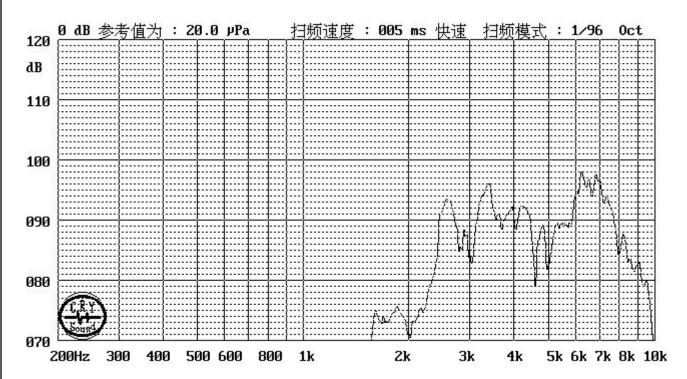


Unit:mm Tolerance: ±0.5mm

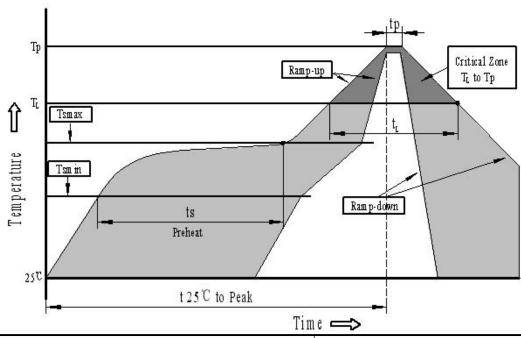
# D. RECOMMEND DRIVING CIRCUIT



# **E.FREQUENCY CURVE**



# F.RECOMMENDED TEMP. PROFILE FOR REFLOW OVEN



	SAME CONTRACT OF STATE OF STAT
Profile Feature	Pb-Free Assembly
Average ramp-up rate(T <sub>L</sub> to Tp)	3°C/second max.
Preheat	
-Temperature Min.(Ts <sub>min</sub> )	150℃
-Temperature Min.(Ts <sub>max</sub> )	200℃
-Temperature Min.(ts)	60∼180 seconds
Ts <sub>max</sub> to T <sub>L</sub>	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
- Temperature(T∟)	217℃
-Time( $T_L$ )	60∼150 seconds
Peak temperature(Tp)	245℃+0/-5℃
Time within 5℃of actual Peak temperature (tp)	6 seconds max.
Ramp-down Rate	6℃/second max.
Time 25°C to Peak Temperature	8 minutes max.

# **G.RELIABILTY TEST**

NO.	ITEM	TEST CONDITION AND REQUIREMENT		
1	High Temperature Test (Storage)	After being placed in a chamber with +80°C for 96 hours and then being placed in normal condition for 4 hours.		
		Allowable variation of SPL after test: 10dB.		
2	Low Temperature Test (Storage)	After being Placed in a chamber with -40°C for 96 hours and then being placed in normal condition for 4 hours.  Allowable variation of SPL after test: 10dB.		
3	Thermal shock test	The part shall be subjected to 10 cycles. One cycle shall consist of::  +80°C  30 min  60 min  then being placed in normal condition for 4 hours.  Allowable variation of SPL after test: 10dB.		
4	Temp./Humidity Cycle test	The part shall be subjected to 10 cycle shall be 24 hours and consist of;  #80°C  a,b:90~98%RH  c:80~98%RH  24hours  then being placed in normal condition for 4 hours.  Allowable variation of SPL after test: 10dB.		
5	Drop Test	Drop on a hard wood board of 4cm thick, any directions ,9 times, at the height of 75cm .  Allowable variation of SPL after test: 10dB.		
6	Vibration Test	After being applied vibration of amplitude of 1.52mmwith 10Hz to 55 Hz to 10Hz band of vibration frequency to each of 3 perpendicular directions for 2 hours ,total 6 hours  Allowable variation of SPL after test: 10dB.		
7	Solderability Test	Lead terminals are immersed in rosin for 5 seconds and then immersed in solder bath of +245 5°C for 3 1 seconds .  90% min. lead terminals shall be wet with solder(Except the edge of terminals).		

8	SolderingHeat Resistance	The product is followed the reflow temperature curve to test its reflow soldering heat resistance.	
9 Terminal Strength Pulling Test		Lead pads shall be soldered on the pc board,the force of 9.8N(1.0kg) is applied to each terminal in axial direction for 10 seconds.  No visible damage and cutting off.	

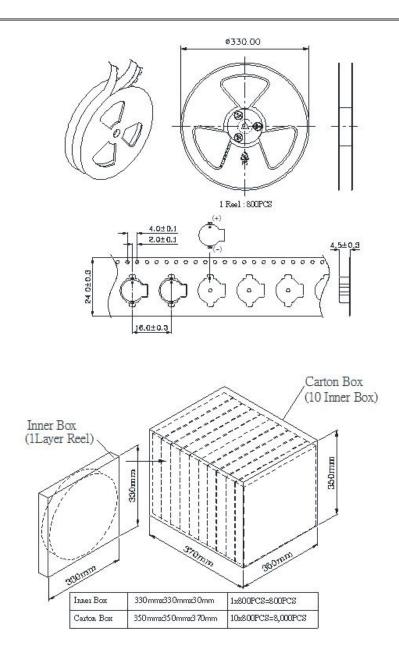
# **H.RELIABILITY TEST**

No.	Item	Test condition	Evaluation standard	
		1.Ordinary temperature	After the test the part	
		The part shall be subjected to 96 hours at room	shall meet specifications	
	Operating life	temperature with 3.6V,2730Hz applied.	without any degradation in	
1	test	2. High temperature	appearance and	
'		The part shall be subjected to 72 hours at +60℃ with	performance except SPL.	
		3.6V,2730Hz applied.	after 4 hours at +25℃,The	
		3.Low temperature	SPL should be in $\pm$	
		The part shall be subjected to 72 hours at -20 ℃ with	10dBA compared with	
	3.6V,2730Hz applied.		initial one.	

### TEST CONDITION

**Standard Test Condition :** a) Temperature :  $+5 \sim +35^{\circ}$ C b) Humidity : 45-85% c) Pressure : 860-1060mbar **Judgment Test Condition:** a) Temperature :  $+25\pm2^{\circ}$ C b) Humidity : 60-70% c) Pressure : 860-1060mbar

## I. PACKING STANDARD



### J.NOTE CAUTIONS

- **a.** Please pay attention in welding process, don't let soldering flux invasion into the sound chamber, otherwise flux can cause defect conduction.
- b. Use should handle with care, avoiding direct pressure contact, or inadvertently falling down, to prevent the occurrence of fault, or the generation characteristics of abnormal movements.
  - C. This product is not dustproof, not waterproof, not resistance to dropping.

### **K. NOTICE ON PRODUCT STORAGE**

**a**. Please store the products in room where the temperature / humidity is stable. And avoid such places where there are large temperature changes. Please store the products under the following conditions :

Temperature: -10 to +40 (degree C)

Humidity: 15 to 85% R.H.

b. Expire date (Shelf life) of the products is 6 months after delivery under the conditions of a sealed and an unopened package. Please use the products within 6 months after delivery. If you store the products for a long time (more than 6months), use carefully because the products may be degraded in the solder-ability and/or rusty. Please confirm solder-ability and characteristics for the products regularly.

C. Please use the products immediately after the package is opened, because the characteristics may be reduced in quality, and/or be degraded in the solder-ability due to storage under the poor condition.

### **L.REVISION**

No.	DATE	DESCRIPTION	REMARK	VERSION
1	Jan.4,2017	Initial condition	TDA-M90040-0327	V1.0
2	Aug.29,2019	Version upgrade	TDA-M90040-0327	V2.0
3	Nov.05	Update packing method	TDA-M90040-0327	V2.1